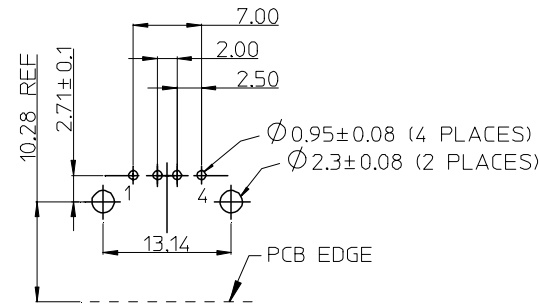
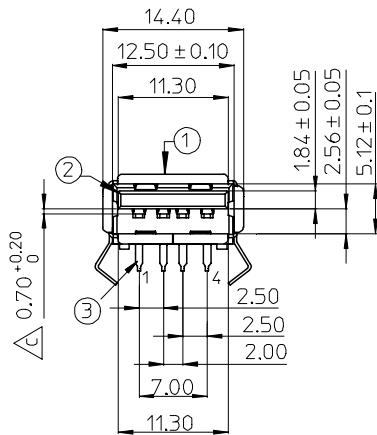
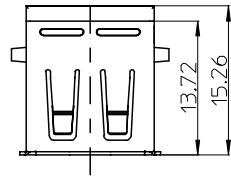
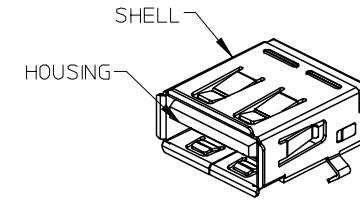
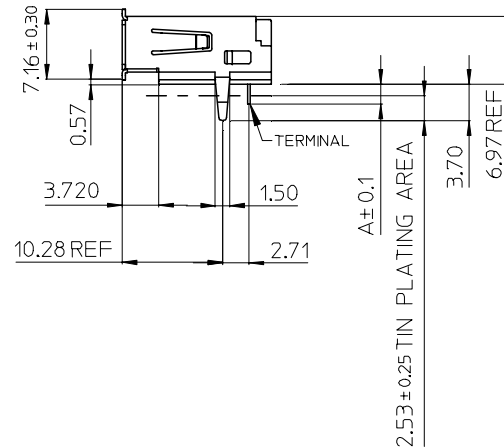




△ PCB LAYOUT (TOP VIEW)



NOTES:

1. MATERIAL:

- ① METAL SHELL: COPPER ALLOY.
- ② HOUSING: SEE CHART, 30% GLASS FIBER FILLED, UL94-V0.
- ③ TERMINAL: PHOSPHOR BRONZE

2. TERMINAL:

- CONTACT AREA: (a) GOLD FLASH.
- (b) GOLD (Au), THICKNESS=30 MICROINCH MINIMUM.
- SOLDER TAIL: TIN PLATED, THICKNESS=75 MICROINCH MINIMUM.
- UNDER PLATED: NICKEL (Ni), THICKNESS=50 MICROINCH MINIMUM.
- METAL SHELL: SEE CHART.

3. RECOMMENDED PCB THICKNESS: SEE CHART

- 4. PRODUCT SPECIFICATION: FOR IR REFER TO PS-67643-002
- FOR NON IR REFER TO PS-67643-003
- 5. TORQUE FORCE SPEC: 2.50kg-cm Min, MEASURED AT BROKEN POINT.
- 6. TEST SUMMARY: FOR IR REFER TO TS-67643-002
- FOR NON IR REFER TO TS-67643-003

7. PACKAGE: REFER TO PK-67643-002

8. LEAD FREE AND ROHS COMPLIANT PRODUCT

REVISE PCB LAYOUT VIEW				QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE		SCALE	DESIGN UNITS	 THIRD ANGLE PROJECTION
EC NO: SH2007-0017					 =0  =0	mm	INCH	MM ONLY		1:1	METRIC	
DRWN:ALLIN 2006/07/14						4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE USB A TYPE RCPT SINGLE RA THROUGH HOLE W/OFLG (LEAD-FREE VERSION)	
CHKD: 2006/07/14						3 PLACES	± ---	± ---	CHECKED BY	DATE		
APPR:WWSCHANG 2006/07/27						2 PLACES	± 0.25	± ---	ALL IN	2005/03/31		
						1 PLACE	± 0.25	± ---	APPROVED BY	DATE		
				ANGULAR ± 3 °			WWSCHANG	2005/03/31	 MOLEX INCORPORATED			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					MATERIAL NO.			DOCUMENT NO.			SHEET NO.	
					SEE TABLE			SD-67643-003			1 OF 2	
					THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

	7	6	5	4	3	2	1																																																																																	
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D	<table><tr><td>P/N</td><td>HOUSING MATERIAL</td><td>COLOR</td><td>CONTACT PLATING</td><td>METAL SHELL PLATING</td><td>REMARK</td></tr><tr><td>67643-0910</td><td>POLYESTER</td><td>BLACK</td><td rowspan="4">GOLD FLASH</td><td rowspan="4">IR REFLOW PROCESS TIN PLATED AT SOLDER AREA THICKNESS=100 MICROINCH MINIMUM UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE) SURFACE APPEARANCE:BRIGHT.</td><td>NON IR</td></tr><tr><td>67643-1910</td><td>POLYESTER</td><td>WHITE</td><td>REFLOW PROCESS</td></tr><tr><td>67643-2910</td><td>HIGH TEMPERATURE NYLON</td><td>BLACK</td><td>FOR IR</td></tr><tr><td>67643-3910</td><td>HIGH TEMPERATURE NYLON</td><td>WHITE</td><td>REFLOW PROCESS</td></tr><tr><td>67643-0911</td><td>POLYESTER</td><td>BLACK</td><td rowspan="4">GOLD PLATING 30 MICROINCH</td><td rowspan="4">NON IR REFLOW PROCESS: TIN PLATED. THICKNESS=80 MICROINCH MINIMUM UNDER PLATE:NICKEL (Ni). SURFACE APPEARANCE:BRIGHT.</td><td>NON IR</td></tr><tr><td>67643-1911</td><td>POLYESTER</td><td>WHITE</td><td>REFLOW PROCESS</td></tr><tr><td>67643-2911</td><td>HIGH TEMPERATURE NYLON</td><td>BLACK</td><td>FOR IR</td></tr><tr><td>67643-3911</td><td>HIGH TEMPERATURE NYLON</td><td>WHITE</td><td>REFLOW PROCESS</td></tr><tr><td colspan="2">PCB THICKNESS</td><td colspan="2">1.60±0.05</td><td colspan="3"></td></tr><tr><td colspan="2">DIMENSION "A"</td><td colspan="2">2.60</td><td colspan="3"></td></tr></table>							P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK	67643-0910	POLYESTER	BLACK	GOLD FLASH	IR REFLOW PROCESS TIN PLATED AT SOLDER AREA THICKNESS=100 MICROINCH MINIMUM UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE) SURFACE APPEARANCE:BRIGHT.	NON IR	67643-1910	POLYESTER	WHITE	REFLOW PROCESS	67643-2910	HIGH TEMPERATURE NYLON	BLACK	FOR IR	67643-3910	HIGH TEMPERATURE NYLON	WHITE	REFLOW PROCESS	67643-0911	POLYESTER	BLACK	GOLD PLATING 30 MICROINCH	NON IR REFLOW PROCESS: TIN PLATED. THICKNESS=80 MICROINCH MINIMUM UNDER PLATE:NICKEL (Ni). SURFACE APPEARANCE:BRIGHT.	NON IR	67643-1911	POLYESTER	WHITE	REFLOW PROCESS	67643-2911	HIGH TEMPERATURE NYLON	BLACK	FOR IR	67643-3911	HIGH TEMPERATURE NYLON	WHITE	REFLOW PROCESS	PCB THICKNESS		1.60±0.05					DIMENSION "A"		2.60																													
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